

REMARKS

Claims 1-9 are pending. Claim 1 is amended and new claim 9 is added.

As a preliminary matter, it is noted that the Examiner still has not acknowledged consideration of the Information Disclosure Statement filed August 3, 2005, even though a request for its return was made in the prior response. The PAIR records do not reflect an entry for the IDS. Accordingly, a copy of the IDS along with a date-stamped post card is attached.

Claims 1, 2 and 8 were rejected under 35 USC §103(a) as being unpatentable over Obata et al. in view of Kong et al. The Examiner acknowledges that Obata et al. does not disclose an element supplementing unit. Kong et al. is cited for allegedly teaching an element supplementing unit. The Examiner argues that it would have been obvious to recognize that after testing the printed wiring board with no defect, additional electronic components would be added. Thus, it appears that the Examiner considers the sockets 35 of Kong et al. as corresponding to an element supplementing unit. This rejection is respectfully traversed.

There would have been no motivation to combine the references as asserted by the Examiner. The claimed invention is directed to a test apparatus, the test apparatus comprising a probe that detects defects in the multilayer wiring board under fabrication; and an element supplementing unit that mounts additional elements on the multilayer wiring board under fabrication when no defect is detected by the probe. Thus, when only defects are not detected, another component is added.

As acknowledged by the Examiner, Obata et al. does not teach an element supplementing unit. Kong et al. also does not teach an element supplementing unit as claimed. That is, Kong et al. does not teach a unit which mounts additional elements on the multilayer wiring board under fabrication when no defect is detected by the probe. Kong et al. merely discloses sockets 35 which can be mounted on a printed circuit board. One of ordinary skill in the art would not have considered combining Obata et al. with Kong et al. Although Kong et al. teaches that devices which can be mounted include integrated circuits for testing, Kong et al. does not teach use of a probe.

Claim 1 has been amended so as to further distinguish the element supplementing unit from the cited art.

Claim 3 was rejected under 35 USC §103 as being unpatentable over Obata et al. in view of Kong et al. in further view of Quattrini et al. In this rejection, the Examiner acknowledges that Obata et al. and Kong et al. fail to disclose the features set forth in claim 3.

The Examiner considers Quattrini et al. as teaching a multilayer wiring board 10 to mount additional elements 12 on a first side and additional elements 12 on a second side. However, the printed circuit board of Quattrini et al. illustrated in Fig. 1 is one which has been produced, and thus can not be considered as a multilayer wiring board under fabrication, and thus would not be possible to mount additional elements on the multilayer wiring board under fabrication when no defect is detected by the probe.

Amendment
Serial No. 10/664,930
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New claim 9 has been added which specifies an element supplementing unit which comprises a thermosetting resin, and the thermosetting resin is cured when a defect is detected by the probe. The cited art fails to teach or suggest the features set forth in new claim 9.

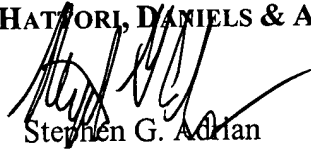
For at least the foregoing reasons, the claimed invention distinguishes over the cited art and defines patentable subject matter. Favorable reconsideration is earnestly solicited.

Should the Examiner deem that any further action by applicant would be desirable to place the application in condition for allowance, the Examiner is encouraged to telephone applicant's undersigned attorney.

If this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

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Attachments: Copy of Information Disclosure Statement
Filed August 3, 2005 w/Date-Stamped Postcard



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Applicant: Naoki NAKAMURA
Papers filed herewith on: August 3, 2005

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Filed: September 22, 2003

\$180.00 – IDS; PTO/SB/08 and Documents



COMMISSIONER OF PATENTS

Receipt is hereby acknowledged of the papers filed as indicated
in connection with the above-identified case.

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